MSP430FR2532 Device Erratasheet

1 Revision History

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev A
ADC50	✓
ADC63	✓
CPU21	✓
CPU22	✓
CPU40	✓
CPU46	✓
EEM23	✓
PORT28	✓
USCI42	✓
USCI45	✓

2 Package Markings

RGE24 *QFN (RGE), 24 Pin*

YM = Year and Month Date Code
LLLL = Assembly Lot Code
S = Assembly Site Code
# = Die Revision
○ = Pin 1

3 Detailed Bug Description

ADC50 *ADC Module*

Function Erroneous ADC conversion result for internal temperature sensor in LPM3 mode

Description When ACLK is used as ADC clock source and device is in LPM3 mode while sampling the on-chip temperature sensor, the ADC may generate erroneous conversion results.

Workaround 1) Use SMCLK or MODCLK as the ADC clock source. A 100us sampling time is required if triggering ADC conversion from LPM3.

OR

2) Use LPM0 or Active Mode.

ADC63 *ADC Module*

Function ADCHI/ADCLO may be reset unexpectedly when ADCCTL2 high byte is written byte-wise

Description ADCHI/ADCLO may be reset unexpectedly when ADCCTL2 high byte is written byte-wise.

Workaround Write to ADCCTL2 high byte in word-wise method.

CPU21 *CPUXv2 Module*

Function Using POPM instruction on Status register may result in device hang up

Description When an active interrupt service request is pending and the POPM instruction is used to set the Status Register (SR) and initiate entry into a low power mode , the device may hang up.

Workaround None. It is recommended not to use POPM instruction on the Status Register.

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below. --silicon_errata=CPU21
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU22 *CPUXv2 Module*

Function Indirect addressing mode with the Program Counter as the source register may produce unexpected results

Description When using the indirect addressing mode in an instruction with the Program Counter (PC) as the source operand, the instruction that follows immediately does not get executed.

For example in the code below, the ADD instruction does not get executed.

```
mov @PC, R7
```

```
add #1h, R4
```

Workaround Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below. --silicon_errata=CPU22
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU40 *CPUXv2 Module*

Function PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section

Description If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in

RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.

For example, a conditional jump instruction followed by data section (0140h).

@0x8012 Loop DEC.W R6

@0x8014 DEC.W R7

@0x8016 JNZ Loop

@0x8018 Value1 DW 0140h

Workaround In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v5.51 or later	For the command line version add the following information Compiler: --hw_workaround=CPU40 Assembler:-v1
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	
MSP430 GNU Compiler (MSP430-GCC)	Not affected	

CPU46 *CPUXv2 Module*

Function POPM peforms unexpected memory access and can cause VMAIFG to be set

Description When the POPM assembly instruction is executed, the last Stack Pointer increment is followed by an unintended read access to the memory. If this read access is performed on vacant memory, the VMAIFG will be set and can trigger the corresponding interrupt (SFRIE1.VMAIE) if it is enabled. This issue occurs if the POPM assembly instruction is

performed up to the top of the STACK.

Workaround If the user is utilizing C, they will not be impacted by this issue. All TI/IAR/GCC pre-built libraries are not impacted by this bug. To ensure that POPM is never executed up to the memory border of the STACK when using assembly it is recommended to either

1. Initialize the SP to

a. TOP of STACK - 4 bytes if POPM.A is used

b. TOP of STACK - 2 bytes if POPM.W is used

OR

2. Use the POPM instruction for all but the last restore operation. For the the last restore operation use the POP assembly instruction instead.

For instance, instead of using:

```
POPM.W #5,R13
```

Use:

```
POPM.W #4,R12
POP.W R13
```

EEM23 *EEM Module*

Function EEM triggers incorrectly when modules using wait states are enabled

Description When modules using wait states (USB, MPY, CRC and FRAM controller in manual mode) are enabled, the EEM may trigger incorrectly. This can lead to an incorrect profile counter value or cause issues with the EEMs data watch point, state storage, and breakpoint functionality.

Workaround None.

NOTE: This erratum affects debug mode only.

PORT28 *PORT Module*

Function Pull-down resistor of TEST/SBWTCK pin

Description The device's internal pull-down resistor on the TEST/SBWTCK pin gets disabled if the SYS control bit SFRRPCR.SYSRSTRE is cleared. This can lead to increased current consumption and unintentionally-enabled JTAG access to the device.

Workaround 1) Do not clear the SFRRPCR.SYSRSTRE bit, use the SFRRPCR.SYSRSTRUP bit to define direction of the internal resistor on RST/NMI/SBWTDIO pin instead.

OR

2) Ensure a zero voltage level of TEST/SBWTCK pin by connecting the pin to an external component (e.g. external pull-down resistor) on the PCB.

USCI42 *eUSCI Module*

Function UART asserts UCTXCPTIFG after each byte in multi-byte transmission

Description UCTXCPTIFG flag is triggered at the last stop bit of every UART byte transmission, independently of an empty buffer, when transmitting multiple byte sequences via UART. The erroneous UART behavior occurs with and without DMA transfer.

Workaround None.

USCI45 *eUSCI Module*

Function Unexpected SPI clock stretching possible

Description In rare cases, during SPI communication, the clock high phase of the first data bit may be stretched significantly. The SPI operation completes as expected with no data loss. This issue only occurs when the USCI SPI module clock (UCxCLK) is asynchronous to the system clock (MCLK).

Workaround Ensure that the USCI SPI module clock (UCxCLK) and the CPU clock (MCLK) are synchronous to each other.

4 Document Revision History

Changes from device specific erratasheet to document Revision A.

1. Device name changed from "XMS" to "MSP430"

Changes from document Revision A to Revision B.

1. Errata ADC63 was added to the errata documentation.

Changes from document Revision B to Revision C.

1. Errata USCI42 was added to the errata documentation.

Changes from document Revision C to Revision D.

1. Errata CPU46 was added to the errata documentation.

Changes from document Revision D to Revision E.

1. CPU21 was added to the errata documentation.
2. USCI45 was added to the errata documentation.
3. CPU22 was added to the errata documentation.
4. Workaround for CPU40 was updated.
5. Workaround for CPU46 was updated.

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